

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2713	(mold or (mold adj resin) or encapsula\$5 or resin or shield\$4 or seal\$4) with (hole or fill\$4 or opening or vent or groov\$4 or passag\$4 or trench or via) and ((cap or top or cover) near3 metal\$4) and ("MEMS")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/04/26 17:53
L2	376	1 and hermetical\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/04/26 17:52
L4	12	2 and temperature and (metal\$3 near2 (cap or top or lid or cover)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/04/26 17:56
L5	329	2 and (gas or liquid or air or water)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/04/26 17:59
L6	317	5 not 4	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/04/26 17:57
L7	13	6 and ("MEMS").ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/04/26 18:03
L8	18	(6 not 7) and ("MEMS").clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/04/26 18:07
S1	55	chen-chien-hua.in.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:13
S2	31	haluzak-charles-c.in.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:13
S3	0	michael-donald.in.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:13
S4	83	chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:13
S5	3302	(packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:14
S6	3302	((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:14
S7	336	(((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:14

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	13	(US-20020185718-\$).did. or (US-4323914-\$ or US-4965660-\$ or US-5198889-\$ or US-5723904-\$ or US-5919329-\$ or US-6038136-\$ or US-6338985-\$ or US-6369449-\$ or US-6388340-\$ or US-6656770-\$ or US-6737750-\$ or US-6772512-\$).did.	US-PGPUB; USPAT	OR	ON	2005/04/26 15:42
L2	28	("4143456" "4915607" "5019673" "5120678" "5169056" "5203076" "5218234" "5239198" "5248710" "5273938" "5292688" "5302850" "5311059" "5371404" "5385869" "5420752" "5450283" "5521435" "5623006" "5656857" "5663106" "5705858" "5814883" "5859470" "5886409" "5973930" "6018188" "6038136").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/26 15:50
L3	4360	(mold or (mold adj resin) or encapsula\$5 or resin or shield\$4 or seal\$4) with (hole or fill\$4 or opening or vent or groov\$4 or passag\$4 or trench) and ((cap or top or cover) near3.metal\$4) and ("MEM" or memory)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/04/26 17:11
L4	510	3 and hermetical\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/04/26 15:54
L5	216	4 and (chip or die or "IC") and temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/04/26 15:55
L6	61	5 and (curing)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/04/26 16:44
L7	21	(6 not 1) and ("MEM" or "MEMS")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/04/26 17:03
L8	40	6 not 7	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/04/26 17:07
L9	11	(5 not 6) and ((mold or (mold adj resin) or encapsula\$5 or resin or shield\$4 or seal\$4) with (hole or fill\$4 or opening or vent or groov\$4 or passag\$4 or trench)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/04/26 17:12
S1	55	chen-chien-hua.in.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:13
S2	31	haluzak-charles-c.in.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:13
S3	0	michael-donald.in.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:13
S4	83	chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:13
S5	3302	(packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:14

S6	3302	((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:14
S7	336	(((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:14
S8	2	(((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) and (fill adj port)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:14
S9	85	((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) not (((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) and (fill adj port)) and (fill\$4 near2 (port or groov\$3 or hole or trench or open\$3))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:17
S10	13	(chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) and (packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:17
S11	16	("20010021570" "20020179921" "20020185737" "20030010808" "20030188881" "5578869" "5596486" "6194789" "6232150" "640009" "6436853" "6441481" "6481570" "6611098" "6627814" "6635509").PN.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:17
S12	2	(((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) and (fill\$3 adj port)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:17
S13	6	((((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) not (((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) and (fill adj port)) and (fill\$4 near2 (port or groov\$3 or hole or trench or open\$3))) and substrate and (metal\$4 with lid)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:17
S14	8	("4751482" "5045922" "5067007" "5081067" "5166773" "5237204" "5306948" "5311059").PN.	USPAT	OR	ON	2005/01/06 18:17
S15	12	"5723904".URPN.	USPAT	OR	ON	2005/01/06 18:17

S16	248	<p>(((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) not ((((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) and (fill adj port))) and (fill\$4 near2 (port or groov\$3 or hole or trench or open\$3))) (chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) (((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) and (fill adj port)) ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) and (packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy)) ("20010021570" "20020179921" "20020185737" "20030010808" "20030188881" "5578869" "5596486" "6194789" "6232150" "6400009" "6436853" "6441481" "6481570" "6611098" "6627814" "6635509").PN.) (((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) and (fill\$3 adj port)) (((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) and (fill adj port))) and (fill\$4 near2 (port or groov\$3 or hole or trench or open\$3))) and substrate and (metal\$4 with lid)) ("4751482" "5045922" "5067007" "5081067" "5166773" "5237204" "5306948" "5311059").PN.) "5723904".URPN.)</p>	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:36
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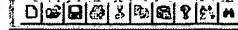
S17	198	<p>((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) not (((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button)))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) and (fill adj port))) and (fill\$4 near2 (port or groov\$3 or hole or trench or open\$3)) (chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) (((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) and (fill adj port)) ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) and (packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy)) ("20010021570" "20020179921" "20020185737" "20030010808" "20030188881" "5578869" "5596486" "6194789" "6232150" "6400009" "6436853" "6441481" "6481570" "6611098" "6627814" "6635509").PN.) (((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) and (fill\$3 adj port)) (((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) and (fill\$4 near2 (port or groov\$3 or hole or trench or open\$3)) and substrate and (metal\$4 with lid)) ("4751482" "5045922" "5067007" "5081067" "5166773" "5237204" "5306948" "5311059").PN.) "5723904".URPN.) and (liquid or gas or water)</p>	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:18
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S18	85	<p>((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) not (((((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) and (fill adj port)) and (fill\$4 near2 (port or groov\$3 or hole or trench or open\$3))) (chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) (((((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) and (fill adj port)) ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) and (packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy)) ("20010021570" "20020179921" "20020185737" "20030010808" "20030188881" "5578869" "5596486" "6194789" "6232150" "6400009" "6436853" "6441481" "6481570" "6611098" "6627814" "6635509").PN.) (((((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) and (fill\$3 adj port)) (((((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) not (((((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and (chip or die or "IC") and (metal\$4 with (cap or button))) not ((chen-chien-hua.in. haluzak-charles-c.in. michael-donald.in.) chen-chien-hua.in.)) and (fill\$4) and ("MEMS" or memory or device) and (hermetical\$3)) and (fill\$4 near2 (port or groov\$3 or hole or trench or open\$3))) and substrate and (metal\$4 with lid)) ("4751482" "5045922" "5067007" "5081067" "5166773" "5237204" "5306948" "5311059").PN.) "5723904".URPN.)) and (liquid or gas or water)) and (coolant or cool\$4)</p>	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/06 18:34
S19	11	("2881370" "4561011" "4612601" "4620215" "4770242" "4914551" "4926242" "4964458" "4965660" "5003429" "5055914").PN.	USPAT	OR	ON	2005/01/06 18:27
S20	41	"5455457".URPN.	USPAT	OR	ON	2005/01/06 18:30

Search History 4/26/2015 04:16:23 Plan-Pluggen.in.) and (fill\$4) and
C:\Documents and Settings\mymemory\My Documents and Settings\mymemory\My
Workspaces\10783849.wsp
((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or epoxy) and
(chip or die or "IC") and (metal\$4 with (cap or button))) not

S25	4	("6442033") or ("6166937") or ("5198889") or ("20020185718").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/01/06 18:50
S26	16	("3586101" "3942586" "4027728" "4103737" "4145708" "4882654" "4884169" "4910642" "4928207" "4949164" "4966226" "4996589" "5019880" "5023695" "5046552" "5077601").PN.	USPAT	OR	ON	2005/01/06 18:53
S27	33640	(chip or die or "IC") and (package or hous\$4 or shield\$4) and (coolant or cool\$4) and (liquid or gas or water) and (lid or top or cap or button)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/07 10:25
S28	1898	((chip or die or "IC") and (package or hous\$4 or shield\$4) and (coolant or cool\$4) and (liquid or gas or water) and (lid or top or cap or button)) and (fill\$4 near2 (port or groove or hole or trench))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/07 10:38
S29	753	(((chip or die or "IC") and (package or hous\$4 or shield\$4) and (coolant or cool\$4) and (liquid or gas or water) and (lid or top or cap or button)) and (fill\$4 near2 (port or groove or hole or trench))) and (media or medium)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/07 10:37
S30	489	((((chip or die or "IC") and (package or hous\$4 or shield\$4) and (coolant or cool\$4) and (liquid or gas or water) and (lid or top or cap or button)) and (fill\$4 near2 (port or groove or hole or trench))) and (media or medium)) and (cave or vacuum)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/07 10:37
S31	341	((((((chip or die or "IC") and (package or hous\$4 or shield\$4) and (coolant or cool\$4) and (liquid or gas or water) and (lid or top or cap or button)) and (fill\$4 near2 (port or groove or hole or trench))) and (media or medium)) and (cave or vacuum)) and substrate and (shield\$3 or seal\$4))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/07 10:38
S32	37	((((((chip or die or "IC") and (package or hous\$4 or shield\$4) and (coolant or cool\$4) and (liquid or gas or water) and (lid or top or cap or button)) and (fill\$4 near2 (port or groove or hole or trench))) and (media or medium)) and (cave or vacuum)) and substrate and (shield\$3 or seal\$4)) and (fill\$4 near2 (port or groove or hole or trench)).clm.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/07 10:39
S33	183	((((((chip or die or "IC") and (package or hous\$4 or shield\$4) and (coolant or cool\$4) and (liquid or gas or water) and (lid or top or cap or button)) and (fill\$4 near2 (port or groove or hole or trench))) and (media or medium)) and (cave or vacuum)) and substrate and (shield\$3 or seal\$4)) and (fill\$4 adj (port or groove or hole or trench))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/07 10:39
S34	18	((((((chip or die or "IC") and (package or hous\$4 or shield\$4) and (coolant or cool\$4) and (liquid or gas or water) and (lid or top or cap or button)) and (fill\$4 near2 (port or groove or hole or trench))) and (media or medium)) and (cave or vacuum)) and substrate and (shield\$3 or seal\$4)) and (fill\$4 adj (port or groove or hole or trench)).clm.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/07 10:42
S35	19	((((((chip or die or "IC") and (package or hous\$4 or shield\$4) and (coolant or cool\$4) and (liquid or gas or water) and (lid or top or cap or button)) and (fill\$4 near2 (port or groove or hole or trench))) and (media or medium)) and (cave or vacuum)) and substrate and (shield\$3 or seal\$4)) and (fill\$4 near2 (port or groove or hole or trench)).clm.) not (((((((chip or die or "IC") and (package or hous\$4 or shield\$4) and (coolant or cool\$4) and (liquid or gas or water) and (lid or top or cap or button)) and (fill\$4 near2 (port or groove or hole or trench))) and (media or medium)) and (cave or vacuum)) and substrate and (shield\$3 or seal\$4)) and (fill\$4 adj (port or groove or hole or trench)).clm.)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/07 10:44

S36	159	(((((chip or die or "IC") and (package or hous\$4 or shield\$4) and (coolant or cool\$4) and (liquid or gas or water) and (lid or top or cap or button)) and (fill\$4 near2 (port or groove or hole or trench))) and (media or medium)) and (cave or vacuum)) and substrate and (shield\$3 or seal\$4)) and (fill\$4 adj (port or groove or hole or trench))) not (((((chip or die or "IC") and (package or hous\$4 or shield\$4) and (coolant or cool\$4) and (liquid or gas or water) and (lid or top or cap or button)) and (fill\$4 near2 (port or groove or hole or trench))) and (media or medium)) and (cave or vacuum)) and substrate and (shield\$3 or seal\$4)) and (fill\$4 near2 (port or groove or hole or trench)). clm.)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/07 10:44
S37	25	(((((chip or die or "IC") and (package or hous\$4 or shield\$4) and (coolant or cool\$4) and (liquid or gas or water) and (lid or top or cap or button)) and (fill\$4 near2 (port or groove or hole or trench))) and (media or medium)) and (cave or vacuum)) and substrate and (shield\$3 or seal\$4)) and (fill\$4 adj (port or groove or hole or trench))) not (((((chip or die or "IC") and (package or hous\$4 or shield\$4) and (coolant or cool\$4) and (liquid or gas or water) and (lid or top or cap or button)) and (fill\$4 near2 (port or groove or hole or trench))) and (media or medium)) and (cave or vacuum)) and substrate and (shield\$3 or seal\$4)) and (fill\$4 near2 (port or groove or hole or trench)). clm.) and ((heat or thermal\$4) adj (spread\$4 or dissipati\$4))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/07 10:45
S38	5	("3953566" "4482516" "4705762" "4985296" "5545473"). PN.	USPAT	OR	ON	2005/01/07 11:10
S39	25	"5919329".URPN.	USPAT	OR	ON	2005/01/07 11:10
S40	10	("4890383" "6107689" "5700981" "5729437" "5776798" "5919329" "5973263" "5981314" "6038136" "6150193"). PN.	USPAT	OR	ON	2005/01/07 11:17
S41	23	("4143456" "4770899" "4859722" "5203076" "5218234" "5249101" "5323947" "5380560" "5385869" "5535101" "5557150" "5581122" "5619070" "5641996" "5700723" "5708304" "5710071" "5731231" "5767446" "5814882" "5827999" "5841192" "5892290").PN:	USPAT	OR	ON	2005/01/07 11:18
S42	15	"6038136".URPN.	USPAT	OR	ON	2005/01/07 11:21
S43	28	("4143456" "4915607" "5019673" "5120678" "5169056" "5203076" "5218234" "5239198" "5248710" "5273938" "5292688" "5302850" "5311059" "5371404" "5385869" "5420752" "5450283" "5521435" "5623006" "5656857" "5663106" "5705858" "5814883" "5859470" "5886409" "5973930" "6018188" "6038136").PN.	USPAT	OR	ON	2005/01/07 11:24
S44	4	"6369449".URPN.	USPAT	OR	ON	2005/01/07 11:26
S45	30	("4323914" "4953005" "5191404" "5289337" "5383269" "5399898" "5475262" "5583321" "5591959" "5600541" "5604377" "5608262" "5661339" "5760478" "5869896" "5963429" "6008536" "6011696" "6084308" "6104084" "6133064" "6133626" "6140144" "6229215" "6239484" "6265771" "6291267" "6369449" "6424033" "6461895"). PN.	USPAT	OR	ON	2005/01/07 11:29
S46	1	"4092697".PN.	USPAT	OR	ON	2005/01/07 11:31
S47	102	"4323914".URPN.	USPAT	OR	ON	2005/01/07 11:32
S48	13	"6338985".URPN.	USPAT	OR	ON	2005/01/07 11:33
S49	15	"6038136".URPN.	USPAT	OR	ON	2005/01/07 11:35
S50	13	"6338985".URPN.	USPAT	OR	ON	2005/01/07 11:36
S51	19	("3953566" "4360562" "4482516" "4705762" "4915981" "4963697" "4985296" "4992318" "5108843" "5294477" "5545473" "5571608" "5778523" "5868887" "5919329" "5970319" "5983974" "5988488" "6015722").PN.	USPAT	OR	ON	2005/01/07 11:38
S52	2	"6504242"	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2005/01/07 11:46
S53	0	"6773963".URPN.	USPAT	OR	ON	2005/01/07 11:51
S54	0	"6773963".URPN.	USPAT	OR	ON	2005/01/07 11:51
S55	9	("4708849" "4817854" "5223741" "5829516" "5913108" "6281573" "6344686" "6504242" "6607942").PN.	USPAT	OR	ON	2005/01/07 11:51



Drafts
 Pending
 Active
 - L1: (2713) (mold or (mold adj resin) or encapsula\$5 or resin
 - L2: (376) 1 and hermetical\$3
 - L3: (329) 2 and (gas or liquid or air or water)
 - L4: (12) 2 and temperature and (meta\$3 near2 (cap or top or
 - L5: (317) 5 not 4
 - L6: (13) 6 and ("MEMS").ti.
 - L7: (18) (6 not 7) and ("MEMS").clm.
 Failed
 - L8: 6 and (cur\$4 or seal\$4 or epoxy or resin)

Saved
 - S1: (55) chen-chien-hua.in.
 - S2: (31) haluzak-charles-c.in.
 - S3: (0) michael-donald.in.
 - S4: (83) chen-chien-hua.in. haluzak-charles-c.in. michael-don

- S5: (3302) (packag\$4 or shield\$4 or hous\$4) and (seal\$4 or ep
 - S6: (3302) ((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or e
 - S7: (336) (((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or e
 - S8: (2) (((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or ep
 - S9: (85) (((((packag\$4 or shield\$4 or hous\$4) and (seal\$4 or e
 - S10: (13) (chen-chien-hua.in. haluzak-charles-c.in. michael-d

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DB: US_PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB

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2 and temperature and (meta\$3 near2 (cap or top or lid or cover)).clm.

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	U	1	PT	P	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20050077584	20050414	18	Hermetically sealed microchip reservoir devices A1	257/414	
2	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20050067688	20050331	72	Structure and method of making capped chips including vertical interconnects A1	257/704	257/778; 257/779;
3	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20050055014	20050310	27	Methods for accelerated release of material from a reservoir device A1	604/890.1	
4	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20040121486	20040624	23	Controlled release device and method using electrothermal ablation A1	436/174	604/890.1
5	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20040108588	20040610	24	Package for microchips A1	257/704	257/E23.193
6	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20040076366	20040422	35	Fiber-attached optical devices with in-plane micromachined mirrors A1	385/18	385/140
7	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20040037535	20040226	8	Hermetic seal for optical waveguide ribbon feed through A1	385/138	
8	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20020179986	20021205	12	MEMS wafer level package A1	257/417	257/E23.193
9	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6763173 B2	20040713	8	Hermetic seal for optical waveguide ribbon feed through	385/138	
10	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6571638 B2	20030603	11	Surface-acoustic-wave pressure sensor and associated methods	73/702	
11	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6452238 B1	20020917	11	MEMS wafer level package	257/415	257/414; 257/532;

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